

## HLT3500LV Thermally Conductive Gel

### BENEFITS AND FEATURES

- Extreme low volatilization
- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- No pump out and cracking

### OVERVIEW

Honeywell HLT3500LV is a two-part, dispensable thermally conductive gel, which offers long-term reliability and superior softness. The enhanced bonding force between the polymer base and the filler largely improves the thermally conductive gel oil separation issue in storage. Prior to curing, the material maintains good thixotropic characteristics and low viscosity to be easily dispensed. The product can be cured in short time after two-component mixing at room temperature. The high compressibility minimizes thermal resistance at interfaces, while maintaining excellent performance during reliability testing.



### TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & power modules

### STORAGE & USE

- Shelf Life 6 months at 0-35°C, <65%RH

Property	HLT3500LV	Test Method
Specific Gravity	3.1	ASTM D792
Viscosity (cps@25°C)	200000-400000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)	50	ASTM D2240
Thermal Conductivity (W/m·K)	3.5	ASTM D5470
Thermal Impedance (°C·in <sup>2</sup> /W) (1mm@10psi) (Typical Value)	0.44	ASTM D5470
Cure Schedule	25°C (hr)	18
	100°C (min)	30
Color	Part A: White Part B: Red	Visual
ΣD3-D20 (PPM)	<50	GC-MS

### Honeywell Electronic Materials

USA: 1-509-252-2102  
 Mainland China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593

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